

BAS116H

75 V, low leakage diode in small SOD123F package

Rev. 02 — 14 December 2009

Product data sheet

1. Product profile

1.1 General description

Low leakage switching diode, encapsulated in a SOD123F small SMD plastic package.

1.2 Features

- Small and flat lead SMD plastic package
- Low leakage current

1.3 Applications

- General-purpose switching



1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		-	-	215	mA
V_R	reverse voltage		-	-	75	V
I_R	reverse current	$V_R = 75\text{ V}$	-	0.003	5.0	nA

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode	[1]	 1  2 <i>sym001</i>
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAS116H	-	plastic surface mounted package; 2 leads	SOD123F

4. Marking

Table 4. Marking codes

Type number	Marking code
BAS116H	B1

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_{RRM}	repetitive peak reverse voltage		-	85	V
V_R	reverse voltage		-	75	V
I_F	forward current		-	215	mA
I_{FRM}	repetitive peak forward current		-	500	mA
I_{FSM}	non-repetitive peak forward current	$t_p = 1 \mu\text{s}$	-	4	A
		$t_p = 1 \text{ ms}$	-	1	A
		$t_p = 1 \text{ s}$	-	0.5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ }^\circ\text{C}$	[1]	375	mW
T_j	junction temperature		-	150	$^\circ\text{C}$
T_{amb}	ambient temperature		-65	+150	$^\circ\text{C}$
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	330	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	70	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

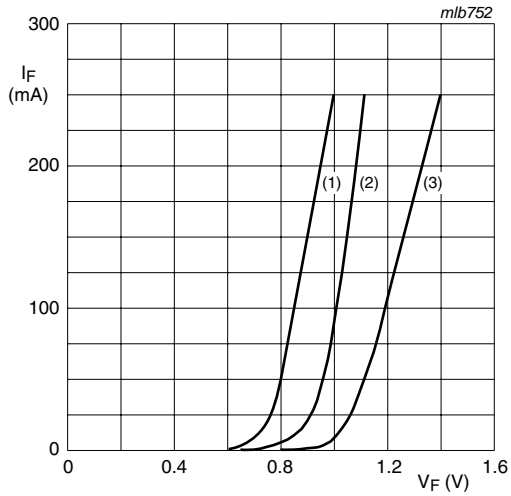
Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	$I_F = 1\text{ mA}$	[1]	-	0.90	mV
		$I_F = 10\text{ mA}$	[1]	-	1.00	mV
		$I_F = 50\text{ mA}$	[1]	-	1.10	mV
		$I_F = 150\text{ mA}$	[1]	-	1.25	mV
I_R	reverse current	$V_R = 75\text{ V}$	-	0.003	5.0	nA
		$V_R = 75\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	3	80.0	nA
C_d	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz}$	-	2	-	pF
t_{rr}	reverse recovery time		[2]	0.8	3.0	μs

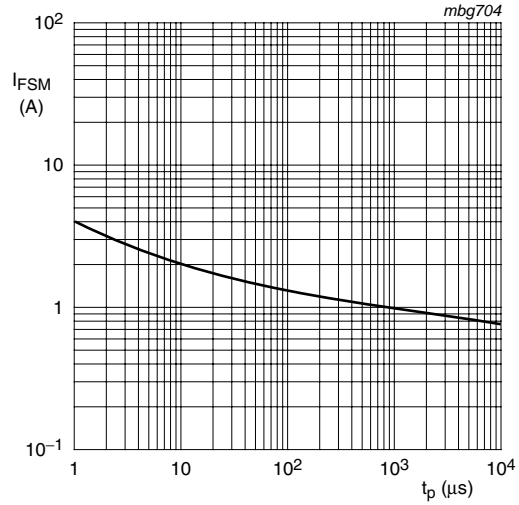
[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

[2] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$.



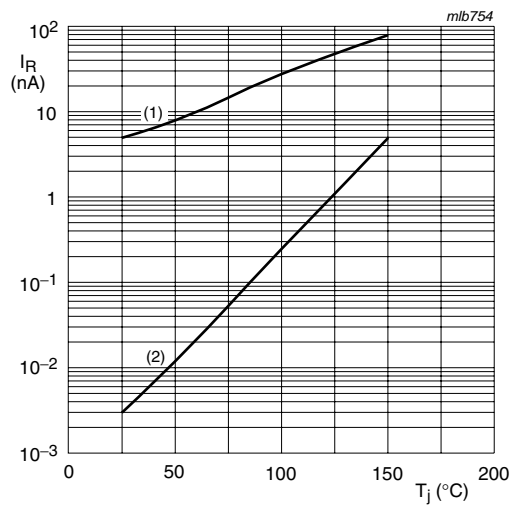
- (1) $T_{amb} = 150\text{ °C}$; typical values
- (2) $T_{amb} = 25\text{ °C}$; typical values
- (3) $T_{amb} = 25\text{ °C}$; maximum values

Fig 1. Forward current as a function of forward voltage



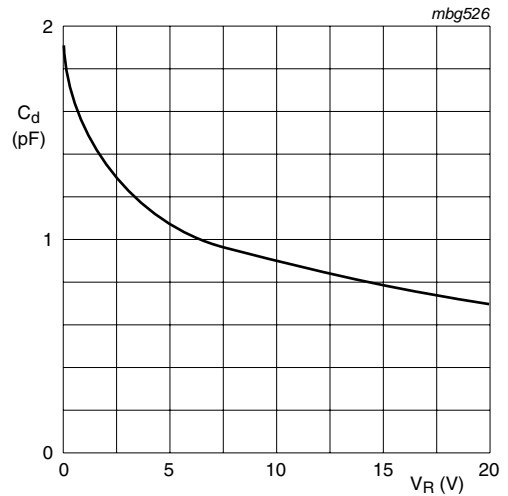
Based on square wave currents
 $T_j = 25\text{ °C}$; prior to surge

Fig 2. Non-repetitive peak forward current as a function of pulse duration



- $V_R = 75\text{ V}$
- (1) Maximum values
 - (2) Typical values

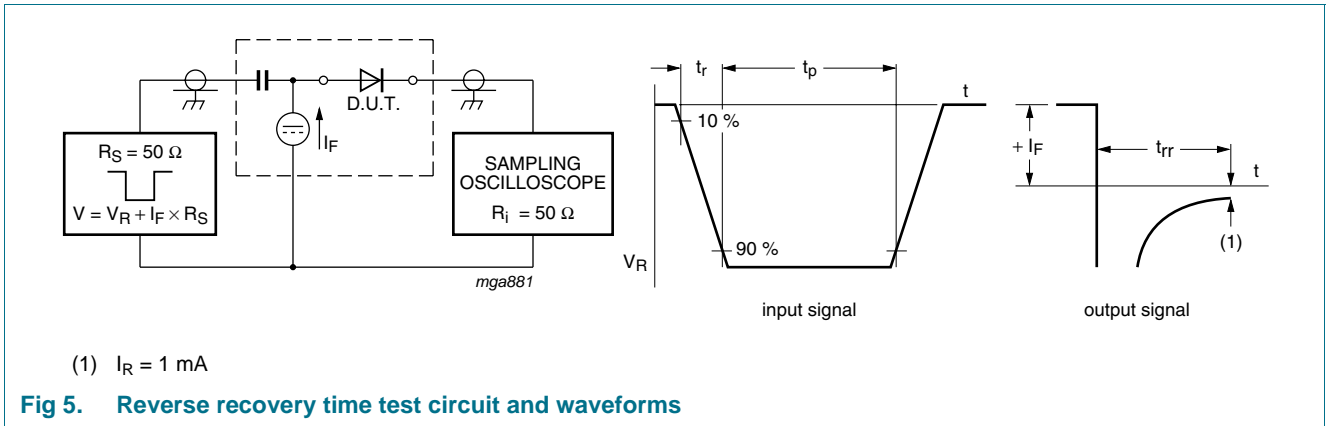
Fig 3. Reverse current as a function of junction temperature



$T_{amb} = 25\text{ °C}$; $f = 1\text{ MHz}$

Fig 4. Diode capacitance as a function of reverse voltage; typical values

8. Test information



9. Package outline

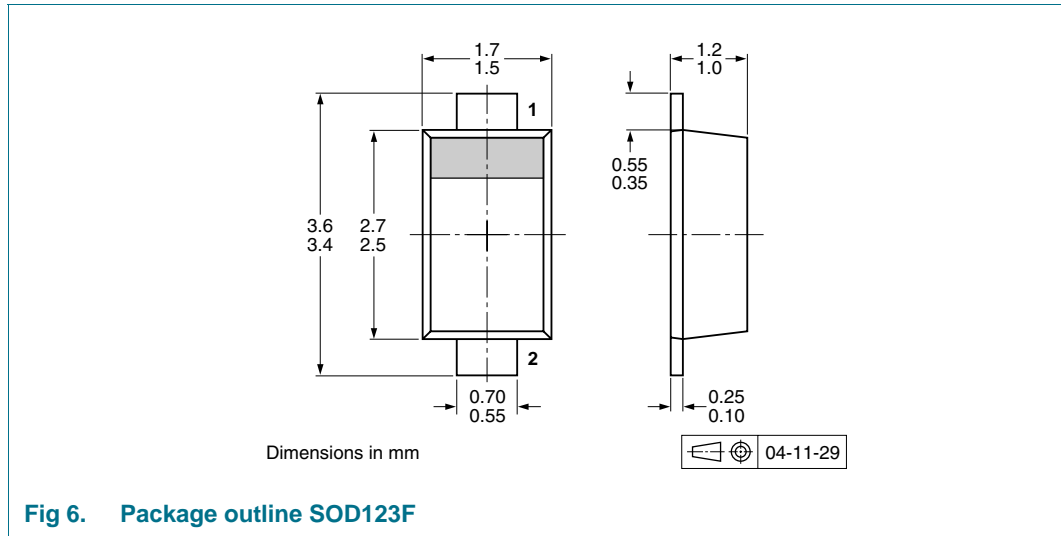


Fig 6. Package outline SOD123F

10. Packing information

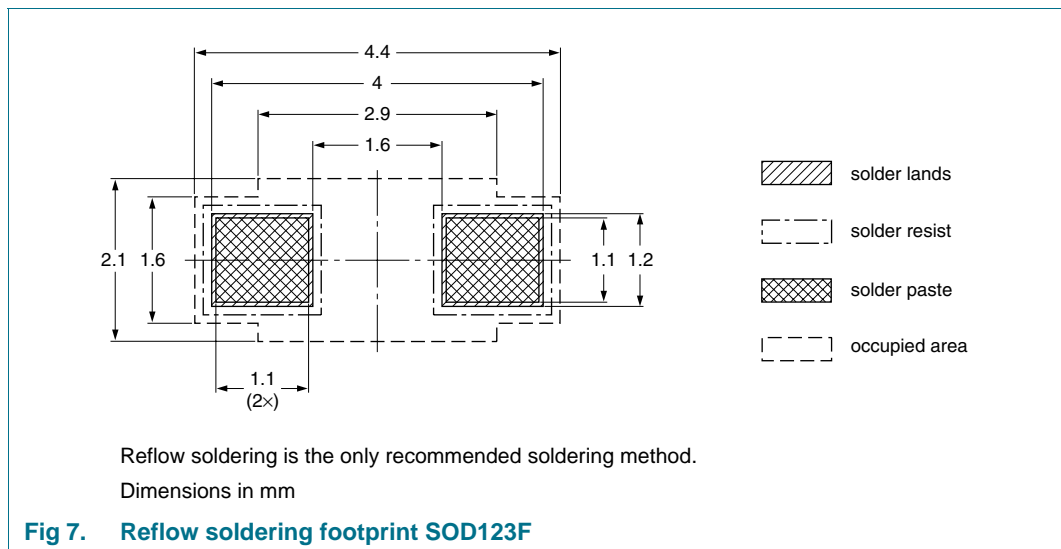
Table 8. Packing methods

The -xxx numbers are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
BAS116H	SO123F	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering



12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS116H_2	20091214	Product data sheet	-	BAS116H_1
Modifications:	<ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.			
BAS116H_1	20050411	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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